



Final Product/Process Change Notification

Document #:FPCN25729ZP

Issue Date:16 Dec 2025

Title of Change:	Wafer Fab Site Addition of onsemi, Bucheon Korea as alternate fab site for ESD and Surge Protection products	
Proposed Changed Material First Ship Date:	01 Jul 2026 or earlier if approved by customer	
Current Material Last Order Date:	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>	
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>	
Product Category:	Active components – Discrete components	
Contact information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Sample Availability Date:	31 Dec 2025	
PPAP Availability Date:	31 Dec 2025	
Additional Reliability Data:	Contact your local onsemi Sales Office	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Change Category		
Category	Type of Change	
Process - Wafer Production	SEM-PW-13: Move all or parts of production to a different wafer fab site.	
Equipment	SEM-EQ-02: Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	
Description and Purpose:		
This Final Product Change Notification (FPCN) is to notify customers of the qualification of onsemi Bucheon, Korea Wafer Fab as an additional wafer fab site for ESD and Surge Protection products.		
Upon expiration of this FPCN, affected parts can be sourced from either onsemi Bucheon, Korea or LA Semiconductor wafer fab.		
	From	To
Manufacturing location for Wafer Fab	LA Semiconductor, Idaho, United States	LA Semiconductor, Idaho, United States onsemi Bucheon, Korea



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Reason / Motivation for Change:	Source/Supply/Capacity Changes																																						
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.																																						
Sites Affected:																																							
onsemi Sites		External Foundry/Subcon Sites																																					
onsemi Bucheon, Korea		None																																					
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code																																						
Reliability Data Summary: QV DEVICE NAME: SZMG2040MUTAG RMS: S103049 PACKAGE: UDFN-18,5.5 x 1.5																																							
<table border="1"><thead><tr><th>Test</th><th>Specification</th><th>Condition</th><th>Interval</th><th>Results</th></tr></thead><tbody><tr><td>High Temperature Reverse Bias</td><td>JESD22-A108</td><td>Ta=150°C, 100% max rated V</td><td>1008 hrs</td><td>0/231</td></tr><tr><td>High Temperature Storage Life</td><td>JESD22-A103</td><td>Ta=150°C</td><td>1008 hrs</td><td>0/231</td></tr><tr><td>Preconditioning</td><td>J-STD-020 JESD-A113</td><td>MSL 1@260°C, TC, uHAST, HAST for surface mount pkgs only</td><td></td><td>0/693</td></tr><tr><td>Temperature Cycling</td><td>JESD22-A104</td><td>Ta= -55°C to +150°C</td><td>1000 cyc</td><td>0/231</td></tr><tr><td>Highly Accelerated Stress Test</td><td>JESD22-A110</td><td>130°C, 85% RH, 18.8psig, bias</td><td>96 hrs</td><td>0/231</td></tr><tr><td>Unbiased Highly Accelerated Stress Test</td><td>JESD22-A118</td><td>130°C, 85% RH, 18.8psig, unbiased</td><td>96 hrs</td><td>0/231</td></tr></tbody></table>					Test	Specification	Condition	Interval	Results	High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231	High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/231	Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C, TC, uHAST, HAST for surface mount pkgs only		0/693	Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231	Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231	Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
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NOTE AEC-1pager is attached. <i>To view attachments:</i> <ol style="list-style-type: none">1. Download pdf copy of the PCN to your computer2. Open the downloaded pdf copy of the PCN3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field4. Then click on the attached file																																							
Electrical Characteristics Summary: Electrical characteristics are not impacted.																																							



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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
SZMG2040MUTAG	#NONE	SZMG2040MUTAG
SZESD7104MUTAG	#NONE	SZMG2040MUTAG
SZESD7016MUTAG	#NONE	SZMG2040MUTAG
SZESD7004MUTAG	#NONE	SZMG2040MUTAG